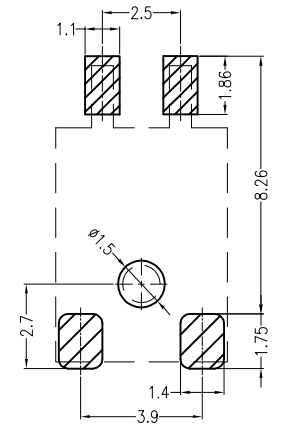
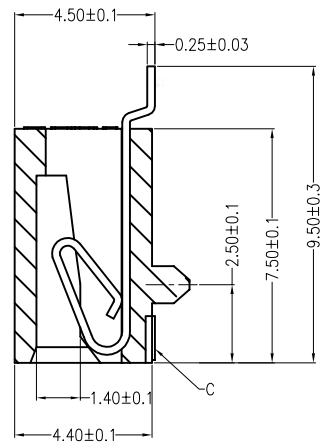
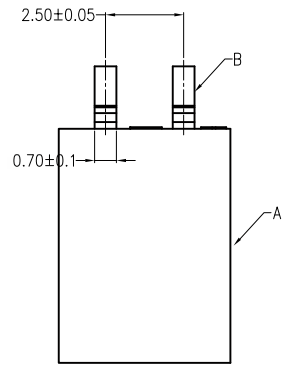
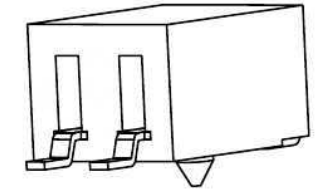


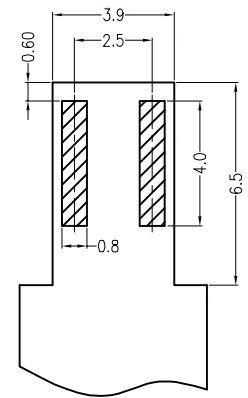
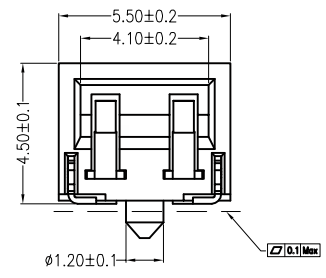
REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



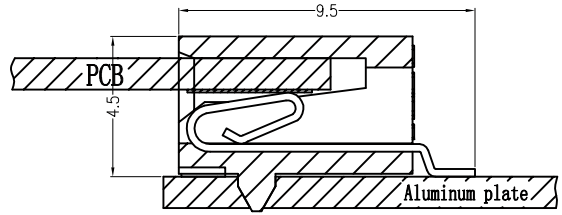
Board Layout



Main Specifications
 Thickness: 1.0mm
 Contact resistance: ≤20mOhm
 Insulation resistance: ≥800MOhm
 Rated voltage: 250V AC DC
 Rated current: 1.0A AC DC
 Withstand Voltage: 1500V AC/minute
 Temperature Range: -25°C --- +105°C



Mating Aluminum plate detail



Assembly Layout

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	Solder Tab	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

LEDsconn			TITLE: - 2.5mmPITCH 90°WAFER SMT TYPE	
X.±0.5	X.±5°	USE: CUSTOMER	PART NO.:	
.X±0.3	.X±2°	APPD: 邵敬和	DWG NO.:	
.XX±0.25	.XX±1°	CHKD: 田峰	SCALE: 1 : 1	
--	--	DR: 周秀龙	SHEET: 1 / 1	
UNITS: mm				